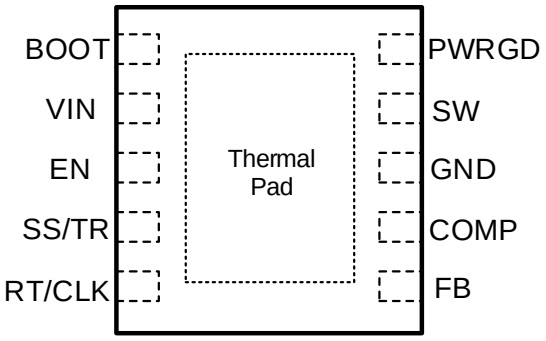
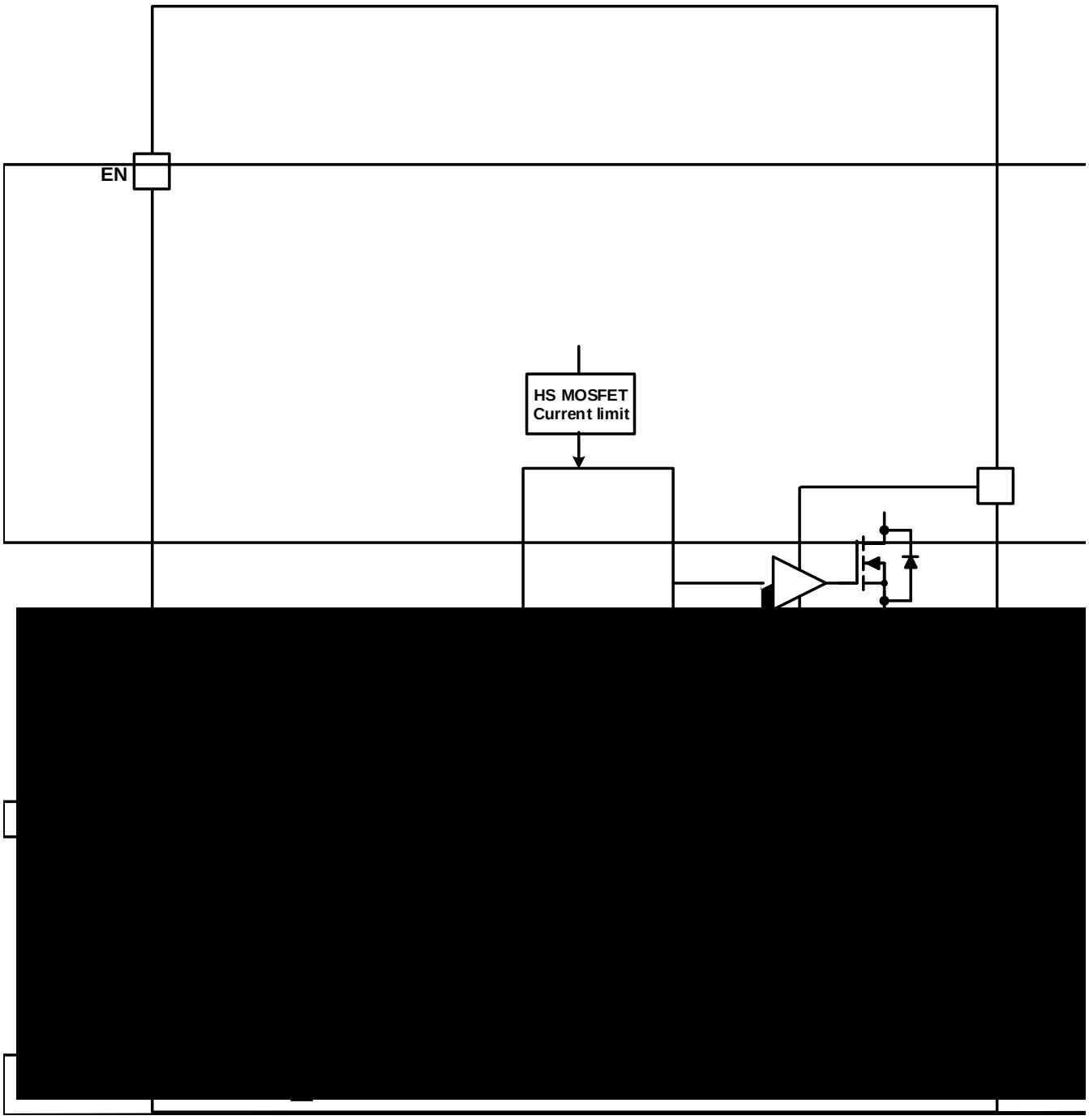
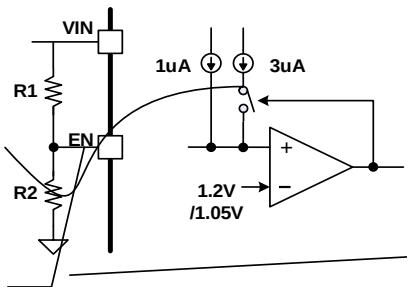
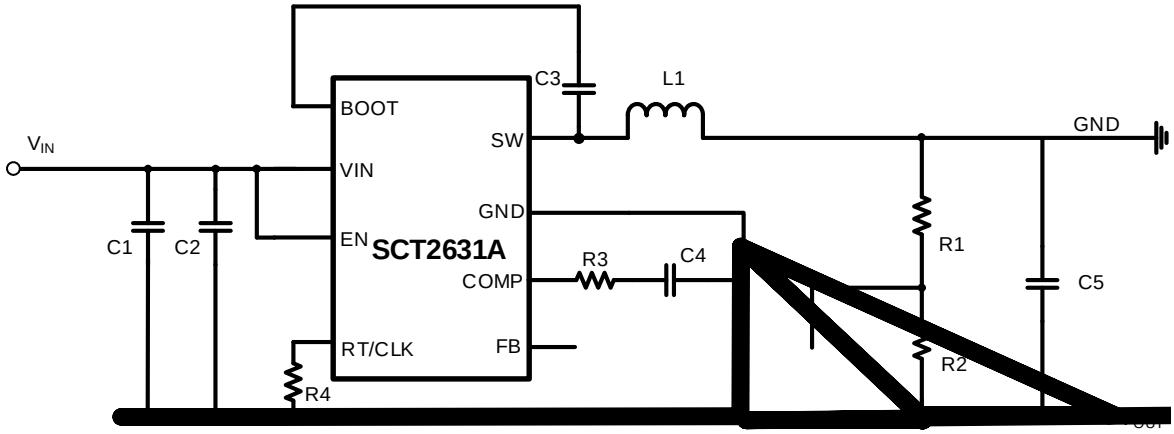
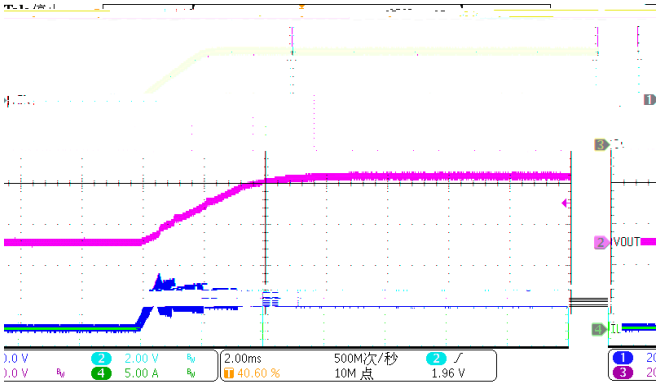
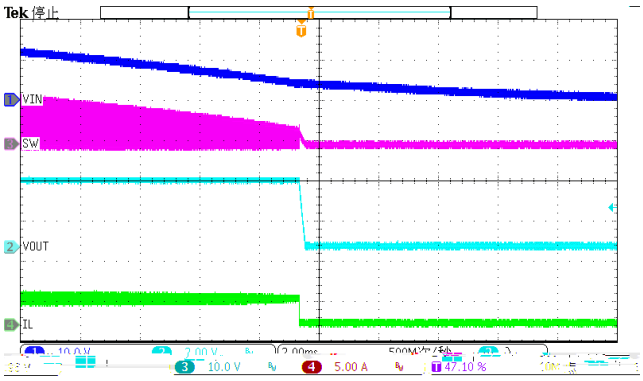

BOOT
VIN
EN
SS/TR
RT/CLK
Thermal
Pad
PWRGD
SW
GND
COMP
FB

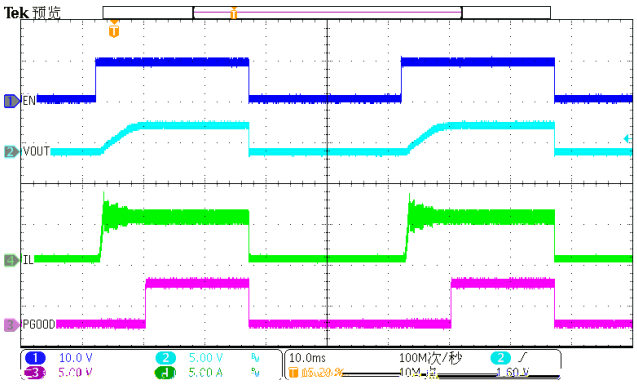

EN
HS MOSFET
Current limit

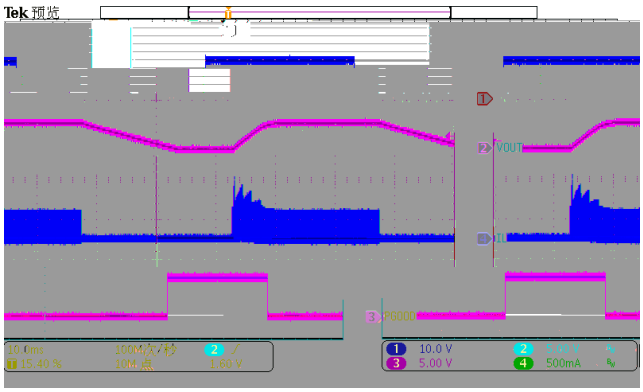

VIN
R1
EN
R2
1uA
3uA
1.2V
/1.05V
+
–

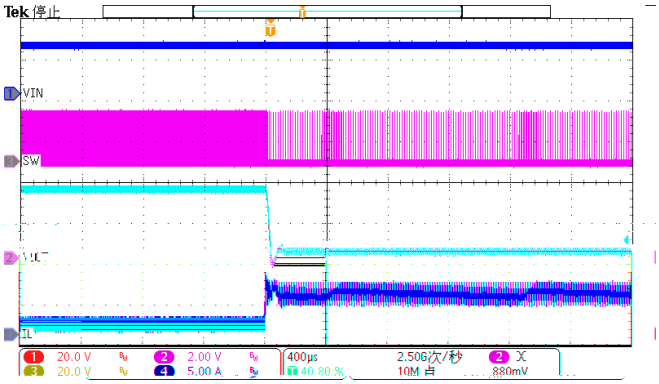

C3
L1
BOOT
SW
GND
VIN
GND
EN
SCT2631A
COMP
RT/CLK
FB
C1
C2
R3
C4
R1
C5
R2
R4

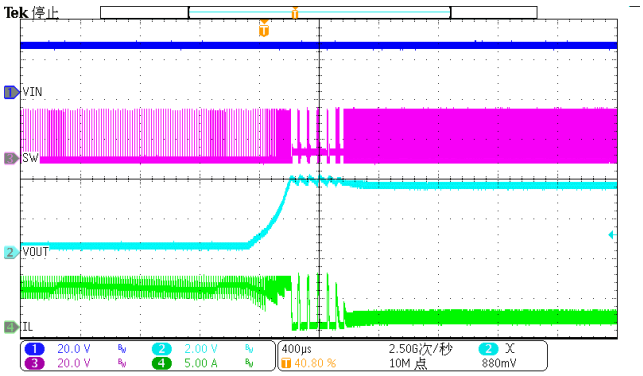

VOUT
IL
2.00ms
500M次/秒
10M 点
1.96 V

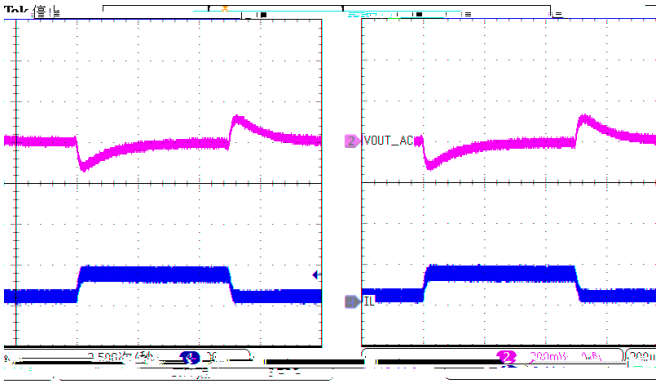

Tek 停止
VIN
SW
VOUT
IL
10.0 V
5.00 A

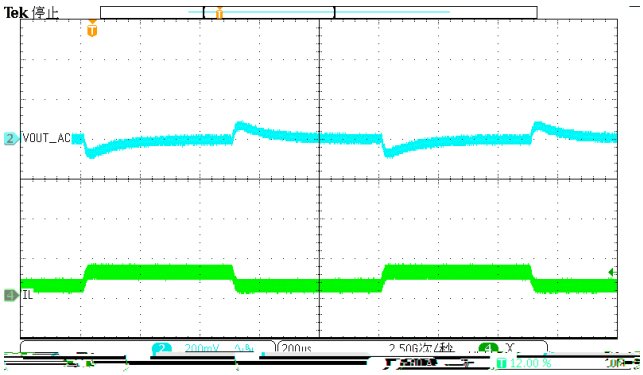

Tek 预览
EN
VOUT
IL
PGOOD
10.0 V
5.00 V
10.0ms
100M次/秒

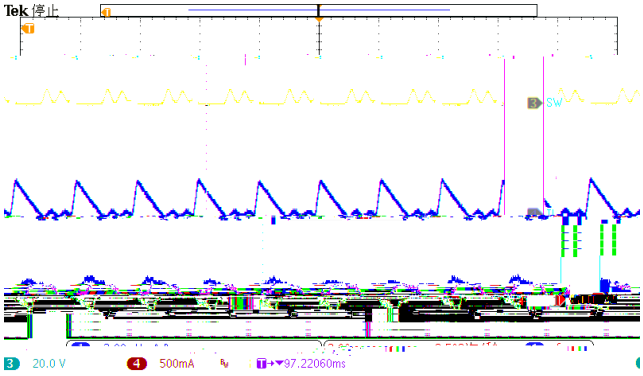

Tek 预览
VOUT
IL
PGOOD
10.0 V
5.00 V
500mA

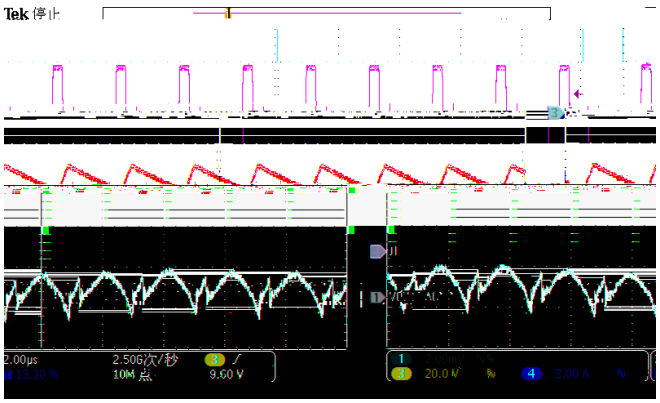

Tek 停止
VIN
SW
VOUT
IL
20.0 V
2.00 V
5.00 A
400µs
2.50G次/秒
10M 点
880mV


Tek 停止
VIN
SW
VOUT
IL
20.0 V
2.00 V
5.00 A
400µs
2.50G次/秒
10M 点
880mV

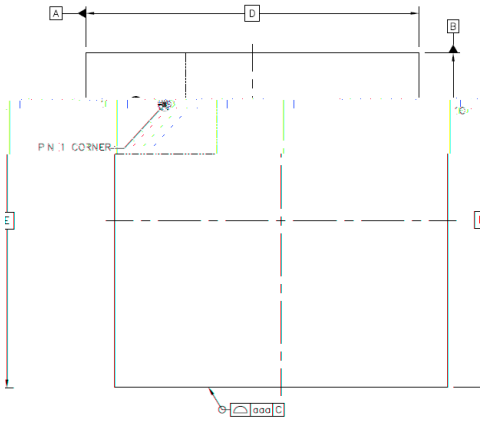

VOUT_AC
IL

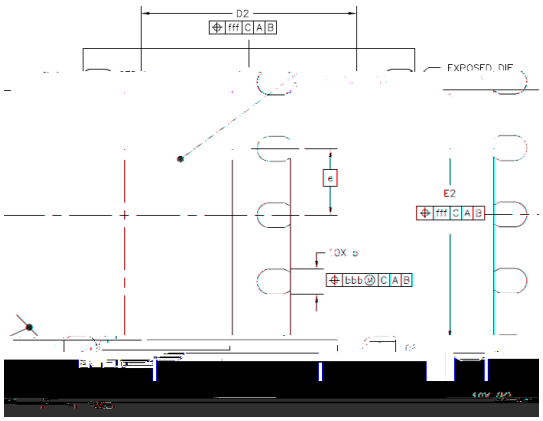

Tek 停止
VOUT_AC
IL

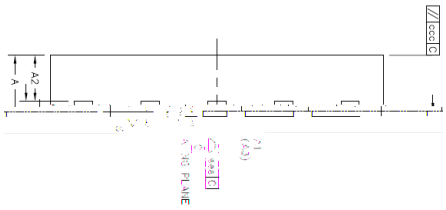

Tek 停止
SW
20.0 V
500mA


Tek 停止
2.00µs
2.50G次/秒
10M 点
9.60 V
20.0 V
2.00 A

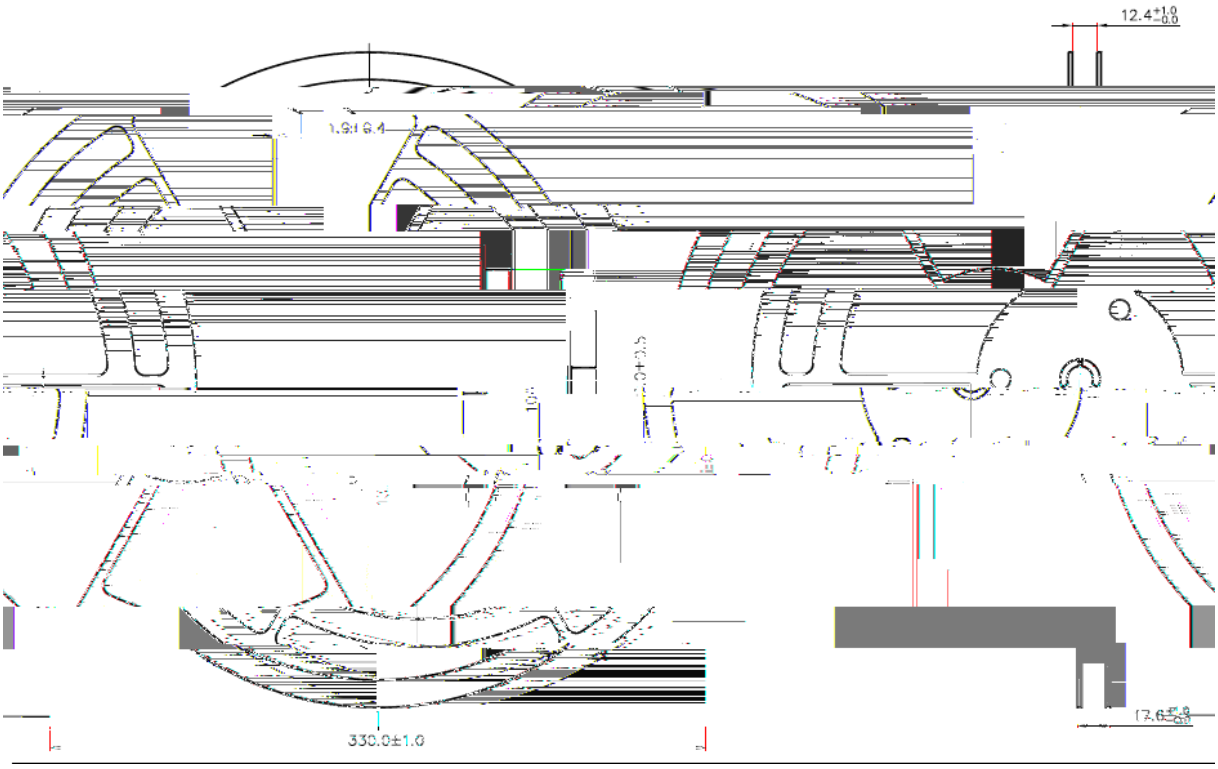
FLUKE
63.6°C
自动 1

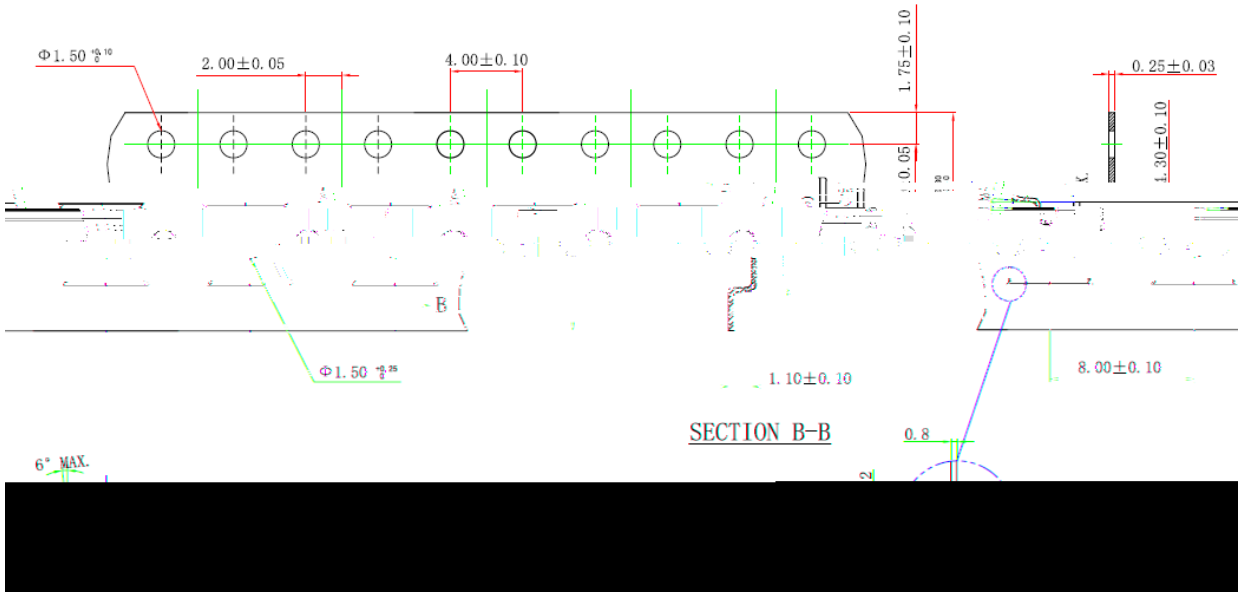






1. Drawing proposed be made a JEDEC package utine MO - 220 variation.
2. Drawing not to scale.
3. All linear dimensions re in millimeters.
4. Thermal pad hall be soldered gn the board.
5. Dimensions f exposed pad gn bottom f package o ot include mold flash.
6. Contact PCB board fabrication for minimum solder mask web Sglerances between the pins.


12.4+1.0 -0.0
330.0±1.0


Φ1.50 +0.10 -0.0
2.00±0.05
4.00±0.10
1.75±0.10
0.05
0.25±0.03
1.30±0.10
B
Φ1.50 +0.25 -0.0
1.10±0.10
8.00±0.10
SECTION B-B
0.8
6° MAX.